2SA2010

Silicon PNP epitaxial planer type

For DC-DC converter

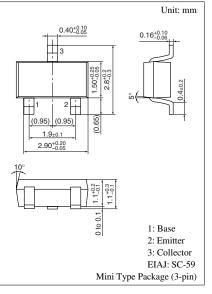
For various driver circuits

Features

- \bullet Low collector to emitter saturation voltage $V_{\text{CE(sat)}}$, large current capacitance
- High-speed switching
- Mini type 3-pin package, allowing downsizing and thinning of the equipment.
- Complementary pair with 2SC5592

Parameter	Symbol	Rating	Unit			
Collector to base voltage	V _{CBO}	-15	V			
Collector to emitter voltage	V _{CEO}	-15	V			
Emitter to base voltage	V _{EBO}	-5	V			
Peak collector current	I _{CP}	-10	А			
Collector current	I _C	-2.5	А			
Collector power dissipation *	P _C	600	mW			
Junction temperature	Tj	150	°C			
Storage temperature	T _{stg}	-55 to +150	°C			

Absolute Maximum Ratings $T_a = 25^{\circ}C$



Marking Symbol: AS

Note) *: Measure on the ceramic substrate at $15 \times 15 \times 0.6$ mm³.

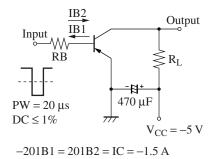
\blacksquare Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector cutoff current	I _{CBO}	$V_{CB} = -10 \text{ V}, I_E = 0$			- 0.1	μΑ
Collector to base voltage	V _{CBO}	$I_{\rm C} = -10 \ \mu A, \ I_{\rm E} = 0$	-15			V
Collector to emitter voltage	V _{CEO}	$I_{\rm C} = -1 {\rm mA}, I_{\rm B} = 0$	-15			V
Emitter to base voltage	V _{EBO}	$I_{\rm E} = -10 \ \mu A, \ I_{\rm C} = 0$	-5			V
Forward current transfer ratio *1	h _{FE1}	$V_{CE} = -2 V, I_C = -100 mA$	200		560	
	h _{FE2}	$V_{CE} = -2 V, I_C = -2.5 A$	100			
Collector to emitter saturation voltage *1	V _{CE(sat)}	$I_{\rm C} = -1$ A, $I_{\rm B} = -10$ mA		-140		mV
		$I_{\rm C} = -2.5 \text{ A}, I_{\rm B} = -50 \text{ mA}$		-270	-320	mV
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		40		pF
Transition frequency	f _T	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}$ f = 200 MHz		180		MHz
Turn-on time *2	t _{on}			35		ns
Storage time *2	t _{stg}			110		ns
Turn-off time *2	t _{off}			10		ns

Note) *1: Rank classification

*2: Reference to the measurement circuit.

Measurement Circuit



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